Full Material Declaration for attached parts list

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Declarations authorised by:
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Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.3%	Nickel REACH Article 67 Exemption	8049-31-8	1%
			Gold	7440-57-5	11.5%
			Polydimethylsiloxane rubber	63394-02-5	25%
			Silicon	7440-21-3	62.5%
Die attach	Lead and Lead alloys	0.2%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	29.9%	Carbon black	1333-86-4	0.3%
			ANTIMONY TRIOXIDE Exempt from industry substance restrictions Exempt from other regulatory requirements	1309-64-4	0.8%
			Tetrabromobisphenol A (TBBPA) Exempt from other regulatory requirements	79-94-7	0.99%
			Epoxy resin 89	26335-32-0	27.61%
			Quartz sand	60676-86-0	70.3%

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Housing	UP (Unsaturated polyester)	24.5%	2-Propenoic acid, 2-methyl-, 1,2-ethanediylbis(oxy-2,1-ethanediyl) ester	109-16-0	100%
Leadfinish	Tin plating	0.1%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	45%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
BxxxR	Bridge Rectifier round	1.2	g